

What is claimed is:

1. An enameled wire comprising an electrical conductive wire and a coating layer formed of a high molecular compound and an inorganic filler material in the form of fine flat particles uniformly dispersed in said high molecular compound.

2. An enameled wire as claimed in claim 1, wherein said inorganic filler material is a clay compound having layer structure.

3. An enameled wire as claimed in claim 1, wherein said inorganic filler material is boron nitride.

4. An enameled wire as claimed in claim 2, wherein said clay compound having layer structure includes at least one mineral selected from a mineral group consisting of smectites, micas and vermiculites.

5. An enameled wire as claimed in claim 4, wherein metal cation existing between adjacent layers of said clay compound is substituted by quaternary ammonium salt.

6. An enameled wire as claimed in claim 1, wherein said high molecular compound is one of polyvinyl formal, polyester, polyester imide and polyamide imide.

7. An enameled wire comprising an electrical conductive wire, a first coating layer surrounding said electric conductive wire, said first coating being formed of a high molecular compound of polyester imide resin solution and an inorganic filler material in the form of fine flat particles uniformly dispersed in said high molecular compound, and a second coating of polyamide imide formed on said first coating layer.

8. An enameled wire as claimed in claim 7, wherein said second coating of polyamide imide is mixed with an inorganic filler material in the form of fine flat particles dispersed therein.

9. An enameled wire comprising an electrically conductive wire, a first coating provided on said electrically conductive wire, said first coating being formed of polyester imide resin, and a second coating layer formed on said first coating layer,

said second coating layer being formed of polyamide imide mixed with an inorganic filler material in the form of fine flat particles uniformly dispersed therein.

10. An enameled wire as claimed in any of claims 1 to 9, wherein said inorganic filler material is in the form of fine flat particles having average particle size of $1\mu\text{m}$ or less and a ratio is 0.5 ~ 15 weight parts of said inorganic filler material to 100 weight parts of said high molecular compound.